PCN Number:		20190522000	PCN Date:	June 5, 2019			
Title: Datasheet for LM3697							
Cu	stomer Contact:	PCN Manager		De	ept:	Quality Services	
Ch	ange Type:						
	Assembly Site		Design			Bump Site	
	Assembly Process		Data Sheet		Wafer Bump Material		
	Assembly Materials		Part number change	ļЦ	Wafer Bump Process		
	Mechanical Spec		Test Site		Wafer Fab Site		
Packing/Shipping/Labeling		Test Process	┦┝┙	Wafer Fab Materials			
					Wafer Fab Process		
Notification Details							
Description of Change: Texas Instruments Incorporated is announcing an information only notification.							
The product datasheet(s) is being updated as summarized below. The following change history provides further details.							
_	n orronin no		SNOS	SCS2D-	NOVEMBER	2013-REVISED MARCH 2019	
Changes from Revision C (October 2015) to Revision D Page							
Changed Table 2 revision register POWER-ON RESET value from 0x00 to 0x01, change silicon revision value in Table 3 from 0000 to 0001							
The datasheet number will be changing.							
Device Family			Change From:		Change To:		
L	LM3697		SNOSCS2C	SNOSCS2D		S2D	
These changes may be reviewed at the datasheet links provided. http://www.ti.com/product/LM3697							
Re	ason for Change	:					
	accurately reflect		tics.				
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):							
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.							
		t identification r	esulting from this PCN:				
Changes to product identification resulting from this PCN:							
None.							
Product Affected:							
	LM3697YFQR						
	· questions regard al Field Sales Repi		mails can be sent to the c	ontac	ts show	n below or your	

Location	E-Mail			
USA	PCNAmericasContact@list.ti.com			
Europe	PCNEuropeContact@list.ti.com			
Asia Pacific	PCNAsiaContact@list.ti.com			
WW PCN Team	PCN_ww_admin_team@list.ti.com			